



**EIE Enterprise (M) Sdn. Bhd.** (944691-T)

## **EIE ST-809 VOC-Free No-Clean Flux**

### **DESCRIPTION**

EIE ST-809 is a VOC-Free, Low solids, halide-free organic no-clean formulation designed for wave-soldering conventional and SMT boards assemblies and is suited for rosin preservative coated bared copper-circuitry, OSP, Tin-plated and HASL printed circuit boards type. This formula is free from VOC (volatile organic compounds) with a vapour pressure higher than 0.1mm Hg @ 20 °C – a guideline for VOC solvents. EIE ST-809 is formulated to maximize and enhanced solderability as priority with minimal post-soldering residue which is non-conductive, non-corrosive and does not need to be removed. This flux is classified as ORL0 per IPC J-STD-004.

### **APPLICATION**

EIE ST-809 is specifically designed for spray or dip fluxing application. For spray fluxing application, air knife blow-away excess flux after spray is recommended to achieve flux uniformity. Flux coating of (450-1300) micrograms/sq inch is generally the optimal desired coating prior pre-heating. Typically it is recommended a preheated temperature of (102 -110) °C as measured on the top/component side of the assembly board be achieved prior entry to wave-soldering. For water-based VOC-free fluxes, a higher preheated top's board assembly is necessary to minimize splattering problem.

### **PHYSICAL PROPERTIES**

Appearance	Clear Straw
Specific Gravity @25°C	1.016 ± 0.005
Solids Content % (w/w)	4.5
Acid Number (mg KOH/g flux)	33.0 ± 0.8
Halide content	0
Flash Point (T.O.C.)	None
Silver Chromate Paper Test	Pass

#### **Surface Insulation Resistance** (As Per ANSI/J-STD-004, IPC-TM-650)

Day 4 (96 hrs) ohm	>3.0 x 10 <sup>10</sup>
Day 7 (168 hrs) ohm	>3.8 x 10 <sup>10</sup>
Minimum requirement (ohm)	1.0 x 10 <sup>8</sup>

### **STORAGE**

Store in well ventilated, No direct sunshine environment

### **PACKING**

25 Litre/carboy